SMTA China South 华南高科技会议 Technical Conference

29th August 2017 (Tuesday) / 2017 年 8 月 29 日(星期二)

(CS17-TC1) Technology Conference / 高科技技术研讨会

Conference Chairman/会议主席:
Henley Zhou 周辉
Member of SMTA China Technical Advisory Committee / 中国 SMTA 技术顾问委员会委员
Director of Advanced Manufacturing Engineering, Asia of Flex / 伟创力亚洲区先进制造工程部总监

Venue/地点	Booth 1T11, Hall 1, Shenzhen Convention & Exhibition Center, Shenzhen, China 中国深圳会展中心 1 号馆 1T11 展位	
Time/时间	**Topic/议题**	**Speaker/主讲人**
10:30 – 11:05	Voiding Control At LED Die Attach Preform Soldering 用焊片进行 LED 芯片贴装工艺时空洞的控制 (CS17-TC1.1)	Fiona Chen 陈芬 Indium Corporation (Suzhou) Co., Ltd. 铟泰科技(苏州)有限公司
11:05 – 11:40	The Study of Cure Percentage Determination for Anisotropic Conductive Film By Ftir Method 关于使用红外光谱法测定异方性导电膜固化率的研究 (CS17-TC1.2)	Henley Zhou 周辉 Flex 伟创力
11:40 – 12:15	Lights Out Electronics Assembly 无人运行的电子组装 (CS17-TC1.3)	Dr. Ranko Vujosevic Ranko Vujosevic 博士 Optimal Electronics Corporation
12:15 – 13:45	**Lunch Break** / 午餐	
13:45 – 14:20	Dielectric Material Characterization for The PCB Pad Cratering Resistance 印刷电路板之介电材料强度抗焊垫坑裂特性研究 (CS17-TC1.4)	Cheng-Chih Chen 陈承志 Integrated Service Technology Inc. 宜特科技股份有限公司
14:20 - 14:55	The Impact of Reduced Solder Alloy Powder Size On Solder Paste Print Performance 减小焊料锡粉尺寸对焊膏印刷性能的影响 (CS17-TC1.5)	Flopy Feng 冯德涛 AIM Solder (Shenzhen) Company Limited 华加美焊材(深圳)有限公司
14:55 - 15:30	Low Insertion Force Compliant Pin Connector Assembly Challenge and Solution 低压入力的压合连接器组装之挑战及解决方案 (CS17-TC1.6)	Kiwi Yu 余秋怡 IBM Procurement China Limited 国际商业机器采购(中国)有限公司
15:30 - 16:05	Failure Analysis Methods Research and Quality Control On Nickel Corrosion of ENIG Solder Joints ENIG 焊点镍腐蚀失效分析方法研究及质量管控 (CS17-TC1.7)	Cong Mei 梅聪 Shenzhen GreatWall Kaifa Technology Co., Ltd. 深圳长城开发科技股份有限公司

All papers will be presented in Chinese 所有演讲者都将使用中文

SMTA China South 华南高科技会议 Technical Conference

30th August 2017 (Wednesday) / 2017 年 8 月 30 日(星期三)

(CS17-TC2)	Technology Conference / 高科技技术研讨会	
Conference Chairman/会议主席: Henley Zhou 周辉 Member of SMTA China Technical Advisory Committee / 中国 SMTA 技术顾问委员会委员 Director of Advanced Manufacturing Engineering, Asia of Flex / 伟创力亚洲区先进制造工程部总监		
Venue/地点	Booth 1T11, Hall 1, Shenzhen Convention & Exhibition Center, Shenzhen, China 中国深圳会展中心 1 号馆 1T11 展位	
Time/时间	**Topic/议题**	**Speaker/主讲人**
10:30 – 11:05	Comparing The Performance of Engineered Tin/Copper Alloys In Selective Soldering 比较特配制锡/铜合金在选择性焊接中的性能 (CS17-TC2.1)	Jackson Chan 陈嘉贤 Alpha Assembly Solutions 爱法组装材料
11:05 – 11:40	Assessment of Solder Paste Technology Limitation At Miniaturization for SIP and SMT Application 焊锡膏技术在微型化后的系统级封装和 SMT 组装应用中的局限性评估 (CS17-TC2.2)	Fiona Chen 陈芬 Indium Corporation (Suzhou) Co., Ltd. 铟泰科技(苏州)有限公司
11:40 – 12:15	Qualification Test for Creep Corrosion Using Flower of Sulfur Chamber 基于硫华方法对电路板爬行腐蚀的验证实验 (CS17-TC2.3)	Dem Lee 李易展 IST Taiwan 台湾宜特科技
12:15 – 13:45	**Lunch Break** / 午餐	
13:45 – 14:20	Electrochemical Migration: How Field Failures Occur and How to Avoid Them 电化学迁移: 产品失效的发生机制和预防方法 (CS17-TC2.4)	Albert Liu 刘君君 ZESTRON Asia North ZESTRON 北亚分公司
14:20 - 14:55	Failure Analysis Case Study of MLCC Component Crack With Application of FEA and Bend Test 关于运用仿真模拟分析和弯曲试验对片式多层陶瓷电容器(MLCC)本体裂纹失效分析的研究 (CS17-TC2.5)	Henley Zhou 周辉 Flex 伟创力
14:55 - 15:30	Flip Chip LED Assembly By Solder Stamping /Pin-Transfer 使用焊膏冲压/针式移印的倒装 LED 芯片装配 (CS17-TC2.6)	Vincent Liu 刘耀升 Alpha Assembly Solutions 爱法组装材料

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Fee / 收费：RMB300/per day (including offical invoice) /人民币 300 元/天(包含发票)

Noted: 1. RMB285/per day for registering before 31 July and RMB540/two days for registering before 31 July
2. Deadline for registration and Conference Fee Collection is 25 August

注: 1. 在 7 月 31 日前登记会议可享受 9.5 折的优惠价(人民币 285 元), 同时报名登记 2 天的会议可享受 9 折的优惠价(人民币 540 元)
2. 报名和收款截止日期是 8 月 25 日

Offer / 提供： 1. SMTA China Technology Conference Attendence Certificate /中国 SMTA 高科技技术研讨会出席证书
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